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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier | | User Part Number | | | | | | |
|---|----------------------------------|--|-------------|-----------|------------|-----------|--|--|
| Nexperia B.V. | | PMEG045V100EPE | | | | | | |
| Name of Laboratory Assembly reliability labs Test | | Part Description | | | | | | |
| | | Nexperia DHAM | Schottky | | | | | |
| | | SMD package | | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # 1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | | | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | | | |
| | PC Dracenditioning | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | | | |
| # 2 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 | | |
| | 11700 | MIL-STD-750-1 M1038 Method A | | | | | | |
| | HTRB High Temperature Reverse | | | | | | | |
| # 5 | Bias | reverse voltage ^[1] | 1000 hours | 206 | 9320 | 0 | | |
| # 3 | Bids | Tevelse voltage | 1000 110015 | 200 | 9320 | 0 | | |
| | тс | JESD22-A104 | | | | | | |
| # 7 | Temperature Cycling | -65 °C to Timax, not to exceed 150°C | 500 cycles | 311 | 14080 | 0 | | |
| | . , , | | 500 07000 | 011 | 11000 | 0 | | |
| | UHAST | JESD22-A118 | | | | | | |
| # 8 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | 96 hours | 311 | 14080 | 0 | | |
| | | JESD22-A102 | | | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | | | |
| # 8a | Autoclave | Pressure = 205 kPa (29.7 psia) | | | | | | |
| | | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | |
| # 9 | Temperature Reverse Bias | rated reverse voltage ^{[1], [2]} | 1000 hours | 311 | 14080 | 0 | | |
| | | MIL-STD-750 Method 1037 | | | | | | |
| | IOL | ton = toff, devices powered to insure ΔT_j = | | | | | | |
| # 10 | Intermittent Operating Life | 100 °C | 333 hours | 312 | 14120 | 0 | | |
| | DCH | | | | | | | |
| # 20 | RSH Resistance to Solder Heat | JESD22-A111 | 10 - | 260 | 0070 | 0 | | |
| # 20 | SD | | 10 s | 269 | 8070 | 0 | | |
| # 21 | SD Solderability | J-STD-002 | | 222 | 6660 | 0 | | |
| | , | J-STD-002 | | 222 | 6660 | U | | |

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab T | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-------------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM S | Schottky | 9320 | 0 | 0,46 | 2,19E+09 |

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